

BEST AVAILABLE COPY

II. SPECIFICATION AMENDMENTS

Please insert the following on page 1, between lines 2 and 3:

BACKGROUND OF THE INVENTION

1. Field of the Invention

Please insert the following on page 1, between lines 5 and 6:

2. Brief Description of Related Developments

Please insert the following on page 2, between lines 6 and 7:

SUMMARY OF THE INVENTION

Please insert the following on page 3, between lines 9 and 10:

BRIEF DESCRIPTION OF THE DRAWINGS

The foregoing aspects and other features of the disclosed
embodiments are explained in the following description, taken
in connection with the accompanying drawings, wherein:

Figures 1 and 2 show schematic depictions of a heat sink
arrangement according to the present invention and an
equipment module that may be inserted into and removed from
the heat sink arrangement;

Figures 3 and 4 show schematic depictions of a an equipment module inserted into a heat sink arrangement according to the present invention;

Figure 5 shows a schematic depiction of a side view of one embodiment of the present invention; and

Figure 6 shows a schematic depiction of another embodiment of the present invention.

Please insert the following on page 3, between lines 10 and 11:

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT(s)

Please insert the following on page 8, at line 9:

What is claimed is:

Please amend the Abstract on page 11 as follows:

ABSTRACT OF THE DISCLOSURE

A heat sink arrangement for modular electronic and/or opto-electronic equipment is provided. The equipment module is inserted into an interface and a heat sink is pivotably arranged so as to be brought into contact with the inserted module. The equipment module may have an angled, or partially

BEST AVAILABLE COPY

angled, so as to assist in bringing the module in contact with the heat sink.

Figure 1.